

ABSTRACT

The present invention relates to a bonding method of bonding a first object to be bonded and a second object to be bonded by a pressurizing operation. The bonding method of the present invention is a first step of causing a first holding member and a second holding member to respectively hold the first object to be bonded and the second object to be bonded in such a manner that a bonding surface of the first object to be bonded and a holding surface of the second object to be bonded face to each other, a second step of treating the bonding surface of the first object to be bonded and the holding surface of the second object to be bonded with a treatment liquid under a condition wherein the first object to be bonded and the second object to be bonded are held by the first holding member and the second holding member, and a third step of pressurizing the first object to be bonded and the second object to be bonded toward each other by the first holding member and the second holding member in order to bond both the bonding surfaces close to each other.

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